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	CERCOORT TEDI	RUART 1995 - REVISE
<ul> <li>Serial Control With Diagnostics</li> <li>Six Power DMOS Transistor Outputs of 350-mA Continuous Current</li> </ul>	(ТОР )	
Internal 60-V Inductive Load Clamp	DRAIN5 1 1 DRAIN4 2	20 V <sub>bat</sub>
Independent ON-State	SCLK 3	18 NC
Shorted-Load/Short-to-Battery Fault	SDI 🛛 4	17 NC
Detection on All Drain Terminals	GND 🖥 5	16 🛛 GND
Independent OFF-State Open-Load Fault	GND [ 6	15 GND
Sense on All Drain Terminals	S <u>DO [</u> ] 7	14 0 NC
Transition of Drain Outputs to Low Duty		
Cycle Pulsed-Width-Modulation (PWM) Mode for Over-Current Condition	DRAIN3 🛛 9 DRAIN2 🚺 10	12 DRAIN1 11 V <sub>CC</sub>
Over-Battery-Voltage-Lockout Protection	DW PA	CKAGE
<ul> <li>Over-Temperature Sense With Serial Interface Fault Status</li> </ul>	(TOP	VIEW)
Fault Diagnostics Returned Through Serial	DRAIN5 🛛 1	24 Vbat
Output Terminal	DRAIN4 🛛 2	23 DRAIN0
Internal Power-On Reset of Registers		22 NC
CMOS Compatible Inputs With Hysteresis	SDI [] 4 GND [] 5	21 NC 20 GND
		19 GND
description	GND 7	18 GND
The TPIC2603 is a monolithic low-side driver which	GND 8	17 GND
provides serial interface and diagnostics to control	SDO 🚺 🤋	16 🛛 NC
six on-board power DMOS switches. Each channel	CS 🛛 10	15 🛛 NC
has independent OFF-state open-load sense,	DRAIN3 🚺 11	14 DRAIN1

six on-board power DMOS switches. Each channel has independent OFF-state open-load sense, ON-state shorted-load/short-to-battery protection, over-battery-voltage-lockout protection, and over-temperature sense with fault status reported through the serial interface. The device also provides inductive voltage transient protection for each drain output. The TPIC2603 drives inductive and resistive loads such as relays, valves, and lamps.

DRAIN3 DRAIN2	11	14   I	ORAIN1
	12	13   V	√CC
NC – No i	nternal	connec	tion

Serial data input (SDI) is transferred through the serial register when  $\overline{CS}$  is low on low-to-high transitions of the serial clock (SCLK). Each string of data must consist of 8 or 16 bits of data. A logic high input data bit turns the respective output channel ON and a logic low data bit turns it OFF.  $\overline{CS}$  must be transited high after all of the serial data has been clocked into the device. A low-to-high transition of  $\overline{CS}$  transfers the last six bits of serial data to the output buffer, places the serial data out (SDO) terminal in a high-impedance state, and re-enables the fault register. Fault data for the device is sent out the SDO terminal. The first bit of the shift register is exclusively ORed with the fault registers. When a fault exists, the SDI data is inverted as it is transferred out of SDO. Fault data consists of fault flags for over-temperature (bit 6) and shorted/open-load (bits 0-5) for each of the six output channels. Fault register bits are set or cleared asynchronously, when  $\overline{CS}$  is high to reflect the current state of the hardware. The fault must be present when  $\overline{CS}$  is transited from high to low to be captured and reported in the serial fault data. New faults cannot be captured in the serial register when  $\overline{CS}$  is low.



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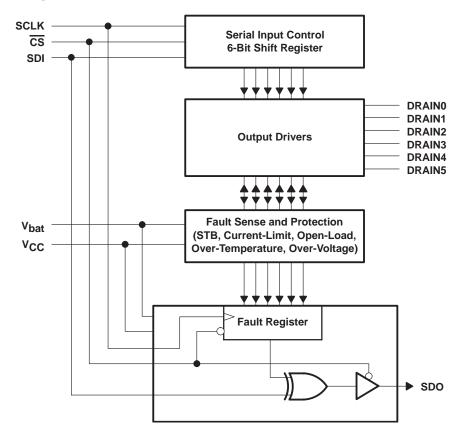
#### description (continued)

When an over-current or shorted-load fault occurs, the channel transits into a low duty cycle pulse-width-modulated (PWM) signal as long as the fault is present. More detail on fault detection operation is presented in the device operation section of this data sheet.

The TPIC2603 provides pulldown resistors on all active-high inputs except SCLK. A pullup resistor is used on  $\overline{CS}$ .

The TPIC2603 is characterized for operation over the operating case temperature of -40°C to 125°C.

#### functional block diagram





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#### **Terminal Functions**

TER	MINAL		
NAME	NO.†	I/O	DESCRIPTION
CS	8 (10)	Ι	Chip select. The $\overline{CS}$ is an active-low input used to select the serial interface of the device. The device accepts serial input data and transmits fault data when $\overline{CS}$ is held low. An internal pullup resistor is provided on the $\overline{CS}$ input.
DRAIN0 DRAIN1 DRAIN2 DRAIN3 DRAIN4 DRAIN5	19 (23) 12 (14) 10 (12) 9 (11) 2 (2) 1 (1)	0	FET drain outputs. The DRAIN terminals are low-side switches for inductive and resistive loads. Each output provides an internal drain-gate clamp to snub inductive transients.
GND	5, 6, 15, 16 (5, 6, 7, 8, 17, 18, 19, 20)	0	Ground. These terminals provide ground return paths for the device.
SCLK	3 (3)	I	Serial clock. The SCLK clocks the shift register. Serial data is transferred into the SDI port and serial fault data is transferred out of the SDO port of the device on the rising edges of SCLK.
SDI	4 (4)	I	Serial data input. The device receives serial data from the control device using the SDI. Serial input data can be configured in 8-bit or 16-bit data words. Refer to Figures 2 and 4 for input protocol. An internal pulldown resistor is provided on the SDI input.
SDO	7 (9)	0	Serial data output. This 3-state output transfers fault data to the control device after the device has been selected by the CS terminal.
V <sub>bat</sub>	20 (24)	Ι	Battery voltage. The V <sub>bat</sub> terminal monitors the battery voltage to detect over-voltage conditions.
VCC	11 (13)	Ι	Supply voltage. The V <sub>CC</sub> terminal receives a 5-V supply for internal logic.

<sup>†</sup> Terminal numbers listed in parenthesis are for the 24-pin DW package.

# absolute maximum ratings over the recommended operating case temperature range (unless otherwise noted)<sup>‡</sup>

Logic supply voltage range, V <sub>CC</sub> (see Note 1)Battery supply voltage range, V <sub>bat</sub>	
Logic input voltage range, $V_1$	
Power DMOS drain-to-source voltage, V <sub>DS</sub> (see Note 2)	
Continuous drain current, each output, all outputs on, $I_D$ , $T_C = 25^{\circ}C$	
Pulsed drain current, single output, $I_{DM}$ , $T_C = 25^{\circ}C$ (see Note 3)	2.25 A
Single-pusle avalanche energy, E <sub>AS</sub> (see Figure 11)	100 mJ
Continuous total power dissipation	. See Dissipation Rating Table
Avalanche current, I <sub>AS</sub> (see Note 4)	1 A
Operating virtual junction temperature range, T <sub>J</sub>	–40°C to 150°C
Storage temperature range, T <sub>stg</sub>	–55°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.

- 2. Each power DMOS source is internally connected to GND.
- 3. Pulse duration  $\leq$  100  $\mu$ s and duty cycle  $\leq$  2%.
- 4. DRAIN supply voltage = 13 V, starting junction temperature (T<sub>JS</sub>) =  $25^{\circ}$ C, L = 150 mH, I<sub>AS</sub> = 1 A (see Figure 11).



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	DISSIPATION RATING TABLE									
PACKAGE	T <sub>C</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>C</sub> = 25°C	T <sub>C</sub> = 125°C POWER RATING							
DW	1750 mW	14 mW/°C	350 mW							
NE	2500 mW	20 mW/°C	500 mW							

### recommended operating conditions

	MIN	NOM	MAX	UNIT
Logic supply voltage, V <sub>CC</sub>	4.5	5	5.5	V
Battery supply voltage, V <sub>bat</sub>	5.5	12	25	V
High-level input voltage, VIH	0.7 V <sub>CC</sub>		VCC	V
Low-level input voltage, VIL	0		0.3 V <sub>CC</sub>	V
Operating case temperature, T <sub>C</sub>	-40		125	°C

## electrical characteristics, $T_C$ = $-40^\circ C$ to 125°C (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>bat</sub>	Battery supply voltage	Normal operation		5.5		25	V
	Dettemport	$V_{CC} = 5 V$				5	mA
lbat	Battery supply current	$\Lambda$ CC = 0				50	μA
VCC	Logic supply voltage			4.5		5.5	V
ICC	Logic supply current	All outputs off,	$V_{bat} = 5.5 V$			5	mA
V <sub>(turn-on)</sub>	V <sub>CC</sub> turn-on voltage (logic operational)	V <sub>bat</sub> = 5.5 V,	Check output functionality			4.5	V
V <sub>(OV)</sub>	Over-battery voltage shutdown	Gate disabled		30		38	V
V <sub>hys(ov)</sub>	Over-battery voltage reset hysteresis			0.4		2	V
		V <sub>bat</sub> = 13 V			0.7	1	
_	Drain-to-source on-state	V <sub>bat</sub> = 5.5 V	$I_{O} = 0.35 \text{ A},  T_{C} = 25^{\circ}\text{C}$		1.7	2.3	0
<sup>r</sup> DS(on)	resistance	V <sub>bat</sub> = 13 V			1.2	1.7	Ω
		$V_{bat} = 5.5 V$	$I_{O} = 0.35 \text{ A},  T_{C} = 125^{\circ}\text{C}$		2.7	3.8	
۱L	On-state current limit			0.8	2	5	А
I <sub>L(sense)</sub>	Over-current sense			0.8	1.5	3	А
IIН	Input pullup current	$GND < V_I < 0.7 \; V_{CC},$	CS input only	-5	-10	-50	μΑ
۱ <sub>IL</sub>	Input pulldown current	$0.3 V_{CC} < V_{I} < V_{CC},$	All other inputs	2.5	10	25	μΑ
I <sub>D(off)</sub>	Off-state drain current	$V_{load} = V_{bat} = 14.5 V$		20	40	80	μA
IO(sleep)	Sleep-state output current	V <sub>bat</sub> < 0.5 V,	$V_{CC}$ < 0.5 V, Load = 14 V			50	μΑ
VOH	High-level serial output voltage	I <sub>O</sub> = 1 mA		0.8 V <sub>CC</sub>			V
V <sub>OL</sub>	Low-level serial output voltage	I <sub>O</sub> = 1 mA			0.2	0.4	V
I <sub>OZ</sub>	High impedance state output current	$V_{CC}$ = 5.5 V to 0 V,	SDO output	-10	1	10	μA
V <sub>(BR)</sub> DSX	Drain-to-source breakdown voltage	dc < 1%,	$t_W = 100 \ \mu s$ , $I_O = 20 \ mA$	52	58	68	V
T <sub>j(sense)</sub>	Thermal flag			150	170	185	°C
Tj(hys)	Thermal flag hysteresis			5	10	15	°C
V <sub>(open)</sub>	Open-load detection voltage			0.3 V <sub>CC</sub>		0.7 V <sub>CC</sub>	V



## switching characteristics, V<sub>CC</sub> = 5 V, T<sub>C</sub> = 25°C

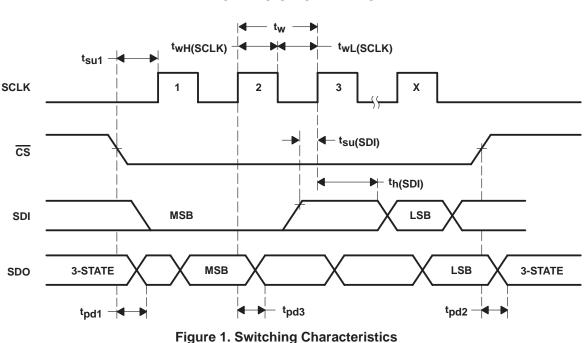
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>w</sub>	Clock cycle period pulse duration, SCLK	See Figure 1		250	555	ns
<sup>t</sup> wH(SCLK)	Pulse duration, SCLK high	See Figure 1		100	248	ns
<sup>t</sup> wL(SCLK)	Pulse duration, SCLK low	See Figure 1		100	248	ns
<sup>t</sup> pd1	Propagation delay from falling edge of $\overline{\text{CS}}$ to SDO valid	CS = 0.8 V to SDO low impedance (see Figure 1)		150	300	ns
<sup>t</sup> pd2	Propagation delay from rising edge of $\overline{CS}$ to SDO 3-state	CS = 2 V to SDO 3-state		150	200	ns
<sup>t</sup> pd3	Propagation delay from SCLK to SDO valid	CS < 0.8 V		80	172	ns
<sup>t</sup> r(SDO)	Rise time of SDO	C <sub>load</sub> = 200 pF		30	50	ns
<sup>t</sup> f(SDO)	Fall time of SDO	C <sub>load</sub> = 200 pF		30	50	ns
<sup>t</sup> (stb)	Short-to-battery/shorted-load/open-load deglitch time	See Figures 5 and 6	25	70	100	μs
<sup>t</sup> d(on)	Turn-on delay time, rising edge of CS to drain		0.4	5	10	
<sup>t</sup> d(off)	Turn-off delay time, rising edge of CS to drain	$V_{\text{bat}} = 14 \text{ V},$	0.4	5	15	_
<sup>t</sup> r(drain)	Rise time of drain terminal	$R_{load} = 30 \Omega$	0.4	5	10	μs
<sup>t</sup> f(drain)	Fall time of drain terminal		0.4	5	10	
f(SCLK)	Serial clock frequency		1.8	4		MHz
tcyc(ref)	Short-to-battery sense cycle time	See Figure 5	1.6	4	6.4	ms
<sup>t</sup> w(sense)	Short-to-battery sense pulse duration	See Figure 5	25	70	100	μs
tsu1	Setup to/from the fall edge of $\overline{CS}$ to the rising edge of SCLK	See Figure 1		150	200	ns
<sup>t</sup> su(SDI)	Setup time, SDI to SCLK	See Figure 1		25	55	ns
<sup>t</sup> h(SDI)	Hold time, SDI after SCLK	See Figure 1		10	55	ns

### thermal resistance

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	All outputs with equal power		50	°C
$R_{\theta JC}$	Junction-to-case thermal resistance	All outputs with equal power		10	°C



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#### serial interface

Control information is transferred into the TPIC2603 through the serial interface. The serial interface consists of a serial clock (SCLK), chip select  $\overline{(CS)}$ , serial data input (SDI), and serial data output (SDO). Serial data is shifted, most significant bit (MSB) first, into the SDI shift register on the rising edge of the first SCLK after  $\overline{CS}$  has transited from high to low. The controller must shift either eight bits or sixteen bits of data into the device with the last six bits of input data containing control information for the output drivers. Data bits preceeding the output control information should be set to 0. A low-to-high transition on  $\overline{CS}$  latches the contents of the last six bits of the serial shift register into the output buffer. A low input to SDI turns the corresponding parallel output OFF and a high input will turn the output ON (see Figure 2).

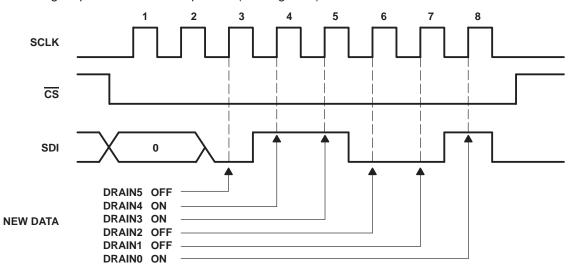


Figure 2. Serial Input Control



### **PRINCIPLES OF OPERATION**

#### serial interface (continued)

Fault isolation data for each channel and global over-temperature status is transferred to the control device using the serial interface. Fault status for the TPIC2603 is captured as  $\overline{CS}$  transits low. The fault interface monitors the SDI terminal and exclusively ORs the respective input control bit with the corresponding fault information bit stored in the fault register. Each exclusive ORed fault bit is transferred out the SDO terminal on the rising edge of the SCLK. Serial data can be transferred in 8-bit or 16-bit words as illustrated in Figure 4, with fault data appearing in the first 8-bits of serial output data. The  $\overline{CS}$  must be transited high after the serial transfer has completely latched the new control data into the output control buffer and re-enable fault reporting on the device (see Figures 3 and 4).

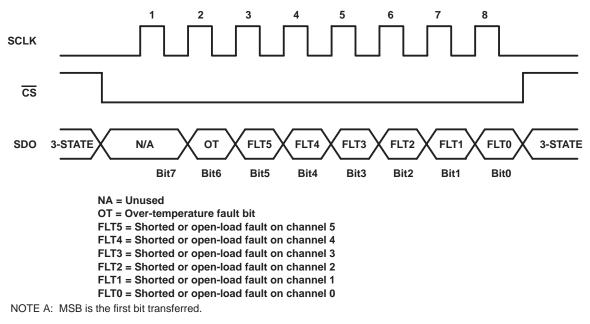


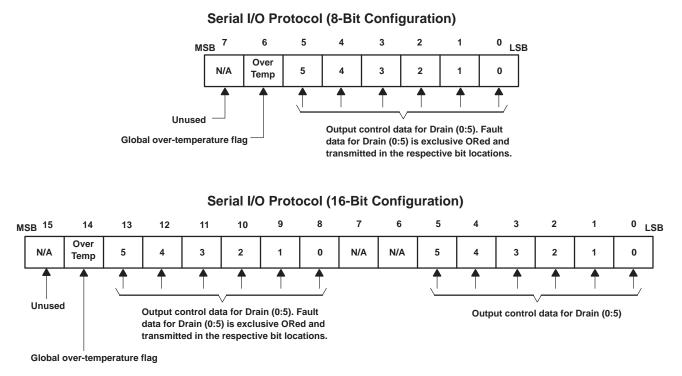
Figure 3. Serial Output Control



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### **PRINCIPLES OF OPERATION**

### serial interface (continued)



NOTE A: MSB is the first bit transferred.





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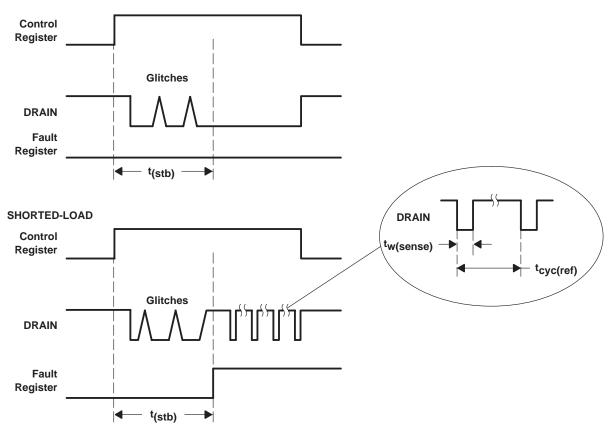
### PRINCIPLES OF OPERATION

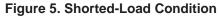
#### fault sense/protection circuitry

#### over-current/short-to-battery sensing and protection

The internal fault protection circuitry of the TPIC2603 monitors the drain current for each channel. Each channel offers two levels of protection from over-current conditions. The first level is a current-limit protection which through the internal FET prevents the switching current from exceeding the on-state current limit. The second level of protection transits the output to a low duty cycle PWM mode when the current exceeds the over-current sense threshold. The PWM mode protection is enabled approximately 70 µs after the output has been turned on. The output remains in the PWM mode until the shorted-load condition has been corrected and then automatically returns to normal operation. Figure 5 illustrates device operation under an over-current or shorted-load condition.

#### NORMAL







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### PRINCIPLES OF OPERATION

#### open-load/short-to-ground sensing

The TPIC2603 checks for open-load and short-to-ground conditions when the output is turned OFF. When the output turns OFF, a 40- $\mu$ A current source switches onto the drain. Under normal conditions, the load provides adequate current to overcome the current source and the drain voltage remains above the open-load detection threshold. When the output is open, then the current source pulls the drain low and an open-load condition is flagged. The open-load test is enabled approximately 70  $\mu$ s after the output turns OFF to allow the drain to stabilize. Figure 6 illustrates device operation under open-load conditions.

#### NORMAL

OPEN-LOAD

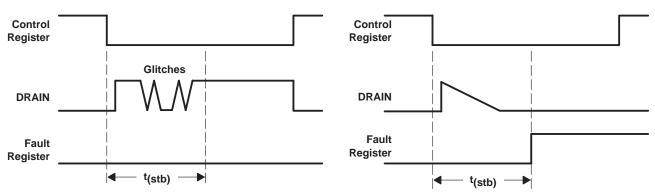


Figure 6. Open-Load Condition

#### over-voltage sensing and protection

The TPIC2603 monitors the V<sub>bat</sub> input terminal to protect the device and load from over-battery voltage conditions. The device disables all of the drain outputs when V<sub>bat</sub> goes above 35 V. An over-battery voltage hysteresis is provided to prevent the outputs from transiting ON and OFF erratically near the over-voltage threshold. The device automatically returns to normal operation after the over-voltage condition has been corrected. Figure 7 illustrates device operation under an over-battery voltage condition.

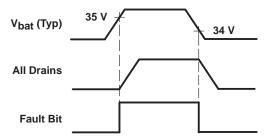


Figure 7. Over-Battery Voltage Condition



### PRINCIPLES OF OPERATION

#### over-temperature sensing

The TPIC2603 monitors the junction temperature of the die to detect over-temperature conditions which may damage the device. When the junction temperature goes above approximately 170°C, the fault logic sets the global over-temperature fault bit. An over-temperature fault is reported using the serial interface on bit 6 (for 8-bit configuration) or bit 14 (for 16-bit configuration). The global over-temperature fault output in the serial data is exclusively ORed with the second bit (bit 6 for 8-bit configuration or bit 14 for 16-bit configuration) of data input to the SDI terminal. Bit 6 or bit 14 of the input data should be set low. Over-temperature faults are for informational purposes only and do not affect the state of the drains. Figure 8 illustrates device operation under over-temperature conditions.

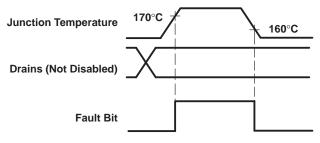
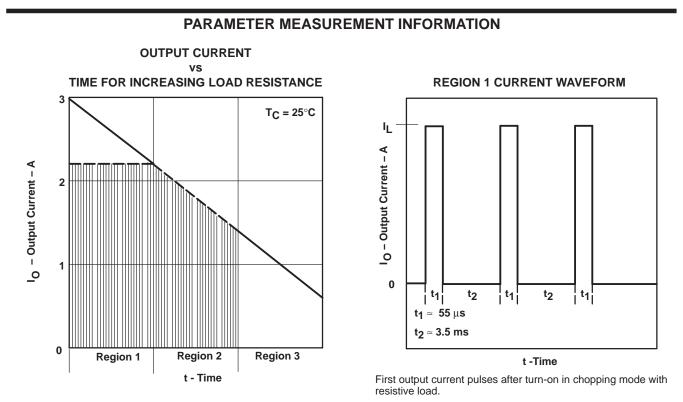


Figure 8. Over-Temperature Sense

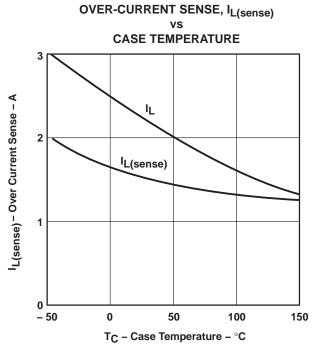


NOTES: A. Region 1 - Analog current limit holds the maximum current while the device runs in chop mode.

- B. Region 2 Analog current limit is removed but device continues in chop mode.
- C. Region 3 Current is below chop mode sense; therefore, it is in normal operation. Variable load is resistance over time.

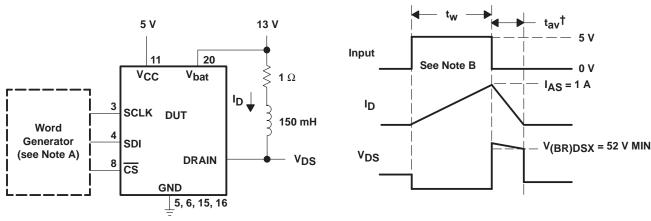
#### Figure 9. Chopping-Mode Characteristics





### PARAMETER MEASUREMENT INFORMATION





Pinout for NE Package Shown

#### SINGLE-PULSE AVALANCHE ENERGY TEST CIRCUIT

VOLTAGE AND CURRENT WAVEFORMS

<sup>†</sup>Non-JEDEC symbol for avalanche time.

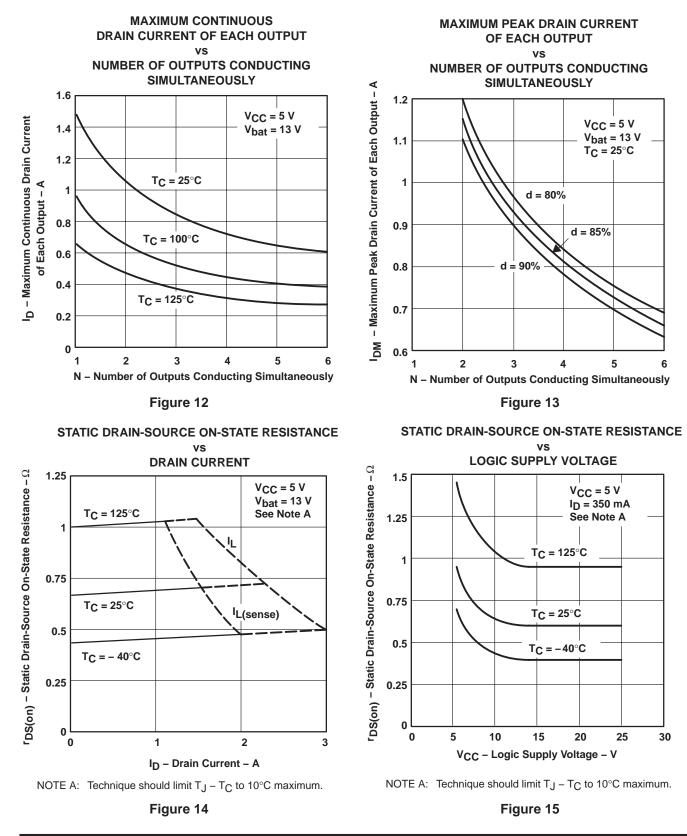
NOTES: A. The word generator has the following characteristics:  $t_f \le 10$  ns,  $t_f \le 10$  ns,  $Z_0 = 50 \Omega$ .

B. Input pulse duration,  $t_W$ , is increased until peak current  $I_{AS} = 1 \text{ A}$ . Energy test level is defined as  $E_{AS} = (I_{AS} \times V_{(BR)DSX} \times t_{aV})/2 = 100 \text{ mJ}$ .

#### Figure 11. Single-Pulse Avalanche Energy Test Circuit and Waveforms

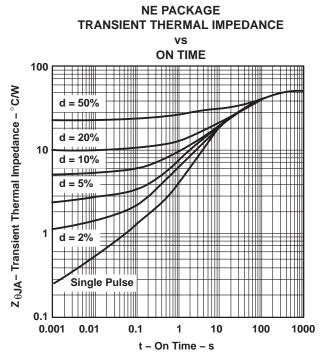






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### THERMAL INFORMATION



The single-pulse curve represents measured data. The curves for various pulse durations are based on the following equation:

$$\begin{split} \mathsf{Z}_{\theta \mathsf{J}\mathsf{A}} \;\; = \;\; \left| \; \frac{\mathsf{t}_{\mathsf{w}}}{\mathsf{t}_{\mathsf{c}}} \; \right| \; \mathsf{R}_{\theta \mathsf{J}\mathsf{A}} \;\; + \;\; \left| \; \mathsf{1} - \frac{\mathsf{t}_{\mathsf{w}}}{\mathsf{t}_{\mathsf{c}}} \; \right| \; \mathsf{Z}_{\theta}(\mathsf{t}_{\mathsf{w}} + \mathsf{t}_{\mathsf{c}}) \\ \\ \; + \;\; \mathsf{Z}_{\theta}(\mathsf{t}_{\mathsf{w}}) \text{-} \mathsf{Z}_{\theta}(\mathsf{t}_{\mathsf{c}}) \end{split}$$

Where:

- $$\label{eq:constraint} \begin{split} \mathsf{Z}_{\theta}(t_{\textbf{W}}) \; = \; & \text{the single-pulse thermal impedance} \\ & \text{for } t = \; t_{\textbf{W}} \; \text{seconds} \end{split}$$
- $\mathsf{Z}_{\theta}(\mathsf{t}_{c})$  = the single-pulse thermal impedance for t =  $\mathsf{t}_{c}$  seconds
- $$\label{eq:constraint} \begin{split} \mathsf{Z}_{\theta} \big( t_{W} \, + \, t_{C} \big) \, = \, & \text{the single-pulse thermal impedance} \\ & \text{for } t = \, t_{W} + t_{C} \, \text{seconds} \end{split}$$

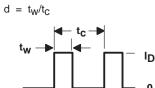


Figure 16





#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
TPIC2603DW	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TPIC2603	Samples
TPIC2603DWG4	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		TPIC2603	Samples
TPIC2603DWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	TPIC2603	Samples
TPIC2603DWRG4	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		TPIC2603	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPIC2603DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
TPIC2603DWRG4	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TEXAS INSTRUMENTS

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## PACKAGE MATERIALS INFORMATION

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPIC2603DWR	SOIC	DW	24	2000	350.0	350.0	43.0
TPIC2603DWRG4	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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